GÃ¶ran N Stemme

List of Publications by Year
in descending order

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226	8,725	41344 49	58581 82
papers	citations	h-index	g-index

226	226	226	6724
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	A valveless diffuser/nozzle-based fluid pump. Sensors and Actuators A: Physical, 1993, 39, 159-167.	4.1	596
2	A valve-less planar fluid pump with two pump chambers. Sensors and Actuators A: Physical, 1995, 47, 549-556.	4.1	245
3	Integrating MEMS and ICs. Microsystems and Nanoengineering, 2015, 1, .	7.0	242
4	A packaged optical slot-waveguide ring resonator sensor array for multiplex label-free assays in labs-on-chips. Lab on A Chip, 2010, 10, 281-290.	6.0	238
5	Low-temperature full wafer adhesive bonding. Journal of Micromechanics and Microengineering, 2001, 11, 100-107.	2.6	219
6	A valve-less diffuser micropump for microfluidic analytical systems. Sensors and Actuators B: Chemical, 2001, 72, 259-265.	7.8	193
7	Micromachined electrodes for biopotential measurements. Journal of Microelectromechanical Systems, 2001, 10, 10-16.	2.5	192
8	Side-opened out-of-plane microneedles for microfluidic transdermal liquid transfer. Journal of Microelectromechanical Systems, 2003, 12, 296-301.	2.5	192
9	Micromachined flat-walled valveless diffuser pumps. Journal of Microelectromechanical Systems, 1997, 6, 161-166.	2.5	165
10	Numerical and experimental studies of flat-walled diffuser elements for valve-less micropumps. Sensors and Actuators A: Physical, 2000, 84, 165-175.	4.1	156
11	Micromachined flow-through filter-chamber for chemical reactions on beads. Sensors and Actuators B: Chemical, 2000, 67, 203-208.	7.8	154
12	Penetration-Enhanced Ultrasharp Microneedles and Prediction on Skin Interaction for Efficient Transdermal Drug Delivery. Journal of Microelectromechanical Systems, 2007, 16, 1429-1440.	2.5	153
13	Wafer-Level Heterogeneous Integration for MOEMS, MEMS, and NEMS. IEEE Journal of Selected Topics in Quantum Electronics, 2011, 17, 629-644.	2.9	140
14	Thermal characterization of surface-micromachined silicon nitride membranes for thermal infrared detectors. Journal of Microelectromechanical Systems, 1997, 6, 55-61.	2.5	135
15	Characterization of micromachined spiked biopotential electrodes. IEEE Transactions on Biomedical Engineering, 2002, 49, 597-604.	4.2	128
16	Painless Drug Delivery Through Microneedle-Based Transdermal Patches Featuring Active Infusion. IEEE Transactions on Biomedical Engineering, 2008, 55, 1063-1071.	4.2	121
17	Real-time intradermal continuous glucose monitoring using a minimally invasive microneedle-based system. Biomedical Microdevices, 2018, 20, 101.	2.8	116
18	A numerical design study of the valveless diffuser pump using a lumped-mass model. Journal of Micromechanics and Microengineering, 1999, 9, 34-44.	2.6	111

#	Article	IF	Citations
19	Novel Microneedle Patches for Active Insulin Delivery are Efficient in Maintaining Glycaemic Control: An Initial Comparison with Subcutaneous Administration. Pharmaceutical Research, 2007, 24, 1381-1388.	3.5	103
20	On-chip temperature compensation in an integrated slot-waveguide ring resonator refractive index sensor array. Optics Express, 2010, 18, 3226.	3.4	99
21	Large-area integration of two-dimensional materials and their heterostructures by wafer bonding. Nature Communications, 2021, 12, 917.	12.8	99
22	A silicon resonant sensor structure for Coriolis mass-flow measurements. Journal of Microelectromechanical Systems, 1997, 6, 119-125.	2.5	97
23	Selective wafer-level adhesive bonding with benzocyclobutene for fabrication of cavities. Sensors and Actuators A: Physical, 2003, 105, 297-304.	4.1	96
24	Hydrophobic valves of plasma deposited octafluorocyclobutane in DRIE channels. Sensors and Actuators B: Chemical, 2001, 75, 136-141.	7.8	94
25	Deep wet etching of borosilicate glass using an anodically bonded silicon substrate as mask. Journal of Micromechanics and Microengineering, 1998, 8, 84-87.	2.6	90
26	A valve-less planar pump isotropically etched in silicon. Journal of Micromechanics and Microengineering, 1996, 6, 87-91.	2.6	85
27	Micromachined filter-chamber array with passive valves for biochemical assays on beads. Electrophoresis, 2001, 22, 249-257.	2.4	85
28	Membrane-sealed hollow microneedles and related administration schemes for transdermal drug delivery. Biomedical Microdevices, 2008, 10, 271-279.	2.8	82
29	Low temperature full wafer adhesive bonding of structured wafers. Sensors and Actuators A: Physical, 2001, 92, 235-241.	4.1	75
30	Performance model for uncooled infrared bolometer arrays and performance predictions of bolometers operating at atmospheric pressure. Infrared Physics and Technology, 2008, 51, 168-177.	2.9	72
31	Highly sensitive triaxial silicon accelerometer with integrated PZT thin film detectors. Sensors and Actuators A: Physical, 2001, 92, 156-160.	4.1	70
32	A fast passive and planar liquid sample micromixer. Lab on A Chip, 2004, 4, 214-219.	6.0	70
33	Valve-less diffuser micropumps fabricated using thermoplastic replication. Sensors and Actuators A: Physical, 1998, 64, 63-68.	4.1	69
34	Expandable microspheres for the handling of liquids. Lab on A Chip, 2002, 2, 117.	6.0	66
35	A sub-micron particle filter in silicon. Sensors and Actuators A: Physical, 1990, 23, 904-907.	4.1	65
36	Fluid density sensor based on resonance vibration. Sensors and Actuators A: Physical, 1995, 47, 327-331.	4.1	64

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37	A high-stroke, high-pressure electrostatic actuator for valve applications. Sensors and Actuators A: Physical, 2002, 100, 264-271.	4.1	64
38	A liquid-triggered liquid microvalve for on-chip flow control. Sensors and Actuators B: Chemical, 2004, 100, 463-468.	7.8	63
39	The fabrication of microfluidic structures by means of full-wafer adhesive bonding using a poly(dimethylsiloxane) catalyst. Journal of Micromechanics and Microengineering, 2007, 17, 1710-1714.	2.6	63
40	Flexible and Stretchable Microneedle Patches with Integrated Rigid Stainless Steel Microneedles for Transdermal Biointerfacing. PLoS ONE, 2016, 11, e0166330.	2.5	59
41	Massively parallel fabrication of crack-defined gold break junctions featuring sub-3â€‰nm gaps for molecular devices. Nature Communications, 2018, 9, 3433.	12.8	59
42	Low-temperature wafer-level transfer bonding. Journal of Microelectromechanical Systems, 2001, 10, 525-531.	2.5	56
43	A disposable sampling device to collect volume-measured DBS directly from a fingerprick onto DBS paper. Bioanalysis, 2015, 7, 2085-2094.	1.5	56
44	Development of micromachined hollow tips for protein analysis based on nanoelectrospray ionization mass spectrometry. Journal of Micromechanics and Microengineering, 2002, 12, 682-687.	2.6	55
45	An integrated pressureâ€"flow sensor for correlation measurements in turbulent gas flows. Sensors and Actuators A: Physical, 1996, 52, 51-58.	4.1	54
46	Sealing of adhesive bonded devices on wafer level. Sensors and Actuators A: Physical, 2004, 110, 407-412.	4.1	53
47	A method for tapered deep reactive ion etching using a modified Bosch process. Journal of Micromechanics and Microengineering, 2007, 17, 1087-1092.	2.6	53
48	Low-power microelectromechanically tunable silicon photonic ring resonator add-drop filter. Optics Letters, 2015, 40, 3556.	3.3	52
49	Wafer-level membrane transfer bonding of polycrystalline silicon bolometers for use in infrared focal plane arrays. Journal of Micromechanics and Microengineering, 2001, 11, 509-513.	2.6	51
50	BCB contact printing for patterned adhesive full-wafer bonded 0-level packages. Journal of Microelectromechanical Systems, 2005, 14, 419-425.	2.5	50
51	Mechanically tri-stable, true single-pole-double-throw (SPDT) switches. Journal of Micromechanics and Microengineering, 2006, 16, 2251-2258.	2.6	47
52	Arrays of monocrystalline silicon micromirrors fabricated using CMOS compatible transfer bonding. Journal of Microelectromechanical Systems, 2003, 12, 465-469.	2.5	46
53	Ultra-miniaturization of a planar amperometric sensor targeting continuous intradermal glucose monitoring. Biosensors and Bioelectronics, 2017, 90, 577-583.	10.1	46
54	New small radius joints based on thermal shrinkage of polyimide in V-grooves for robust self-assembly 3D microstructures. Journal of Micromechanics and Microengineering, 1998, 8, 188-194.	2.6	45

#	Article	IF	Citations
55	A method to maintain wafer alignment precision during adhesive wafer bonding. Sensors and Actuators A: Physical, 2003, 107, 273-278.	4.1	43
56	Binary-Coded 4.25-bit W-Band Monocrystallineâ€“Silicon MEMS Multistage Dielectric-Block Phase Shifters. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 2834-2840.	4.6	43
57	Ptâ€“Al₂O₃dual layer atomic layer deposition coating in high aspect ratio nanopores. Nanotechnology, 2013, 24, 015602.	2.6	42
58	High-Yield Passive Plasma Filtration from Human Finger Prick Blood. Analytical Chemistry, 2018, 90, 13393-13399.	6.5	42
59	Characterization of micromachined hollow tips for two-dimensional nanoelectrospray mass spectrometry. Rapid Communications in Mass Spectrometry, 2003, 17, 337-341.	1.5	41
60	Behaviour and design considerations for continuous flow closed-open-closed liquid microchannels. Lab on A Chip, 2005, 5, 682.	6.0	40
61	Crackâ€Defined Electronic Nanogaps. Advanced Materials, 2016, 28, 2178-2182.	21.0	40
62	Active Opening Force and Passive Contact Force Electrostatic Switches for Soft Metal Contact Materials. Journal of Microelectromechanical Systems, 2006, 15, 1235-1242.	2.5	39
63	Wafer bonding with nano-imprint resists as sacrificial adhesive for fabrication of silicon-on-integrated-circuit (SOIC) wafers in 3D integration of MEMS and ICs. Sensors and Actuators A: Physical, 2009, 154, 180-186.	4.1	39
64	An amperometric nitric oxide sensor with fast response and ppb-level concentration detection relevant to asthma monitoring. Sensors and Actuators B: Chemical, 2015, 209, 639-644.	7.8	39
65	Single-nucleotide polymorphism analysis by allele-specific extension of fluorescently labeled nucleotides in a microfluidic flow-through device. Electrophoresis, 2003, 24, 158-161.	2.4	38
66	A High-Yield Process for 3-D Large-Scale Integrated Microfluidic Networks in PDMS. Journal of Microelectromechanical Systems, 2010, 19, 1050-1057.	2.5	37
67	One-Megapixel Monocrystalline-Silicon Micromirror Array on CMOS Driving Electronics Manufactured With Very Large-Scale Heterogeneous Integration. Journal of Microelectromechanical Systems, 2011, 20, 564-572.	2.5	37
68	Patterned self-assembled beads in silicon channels. Electrophoresis, 2001, 22, 3876-3882.	2.4	36
69	Design and Fabrication Aspects of an S-Shaped Film Actuator Based DC to RF MEMS Switch. Journal of Microelectromechanical Systems, 2004, 13, 421-428.	2.5	36
70	A microfluidic device for parallel 3â€D cell cultures in asymmetric environments. Electrophoresis, 2007, 28, 4705-4712.	2.4	36
71	Immobilized oxazoline-containing Ligands in asymmetric catalysisâ€”a review. Bioorganic and Medicinal Chemistry Letters, 2002, 12, 1857-1861.	2.2	35
72	Rapid Melting Curve Analysis on Monolayered Beads for High-Throughput Genotyping of Single-Nucleotide Polymorphisms. Analytical Chemistry, 2006, 78, 2220-2225.	6.5	35

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73	CMOS-Integrated Si/SiGe Quantum-Well Infrared Microbolometer Focal Plane Arrays Manufactured With Very Large-Scale Heterogeneous 3-D Integration. IEEE Journal of Selected Topics in Quantum Electronics, 2015, 21, 30-40.	2.9	35
74	A concept for miniaturized 3-D cell culture using an extracellular matrix gel. Electrophoresis, 2005, 26, 4751-4758.	2.4	34
75	3D Microvascularized Tissue Models by Laserâ€Based Cavitation Molding of Collagen. Advanced Materials, 2022, 34, e2109823.	21.0	34
76	A new silicon gas-flow sensor based on lift force. Journal of Microelectromechanical Systems, 1998, 7, 303-308.	2.5	33
77	A new edge-detected lift force flow sensor. Journal of Microelectromechanical Systems, 2003, 12, 344-354.	2.5	33
78	A disposable lab-on-a-chip platform with embedded fluid actuators for active nanoliter liquid handling. Biomedical Microdevices, 2007, 9, 61-67.	2.8	33
79	A CMOS integrated silicon gas-flow sensor with pulse-modulated output. Sensors and Actuators, 1988, 14, 293-303.	1.7	32
80	Dynamic actuation of polyimide V-groove joints by electrical heating. Sensors and Actuators A: Physical, 1998, 67, 199-204.	4.1	32
81	Low-pressure-encapsulated resonant structures with integrated electrodes for electrostatic excitation and capacitive detection. Sensors and Actuators A: Physical, 1998, 66, 160-166.	4.1	31
82	Self-assembled and self-sorted array of chemically active beads for analytical and biochemical screening. Talanta, 2002, 56, 301-308.	5.5	31
83	Low-Voltage High-Isolation DC-to-RF MEMS Switch Based on an S-shaped Film Actuator. IEEE Transactions on Electron Devices, 2004, 51, 149-155.	3.0	31
84	A micromachined interface for airborne sample-to-liquid transfer and its application in a biosensor system. Lab on A Chip, 2006, 6, 1504-1509.	6.0	31
85	A Thermally Responsive PDMS Composite and Its Microfluidic Applications. Journal of Microelectromechanical Systems, 2007, 16, 50-57.	2.5	31
86	Very high aspect ratio through-silicon vias (TSVs) fabricated using automated magnetic assembly of nickel wires. Journal of Micromechanics and Microengineering, 2012, 22, 105001.	2.6	31
87	3D Freeâ€Form Patterning of Silicon by Ion Implantation, Silicon Deposition, and Selective Silicon Etching. Advanced Functional Materials, 2012, 22, 4004-4008.	14.9	31
88	Scalable Manufacturing of Nanogaps. Advanced Materials, 2018, 30, e1801124.	21.0	31
89	A static turbine flow meter with a micromachined silicon torque sensor. Journal of Microelectromechanical Systems, 2003, 12, 937-946.	2.5	30
90	Micromachined barbed spikes for mechanical chip attachment. Sensors and Actuators A: Physical, 2002, 95, 94-99.	4.1	29

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91	A lift force sensor with integrated hot-chips for wide range flow measurements. Sensors and Actuators A: Physical, 2003, 109, 120-130.	4.1	28
92	Adhesive copper films for an air-breathing polymer electrolyte fuel cell. Journal of Power Sources, 2005, 144, 113-121.	7.8	28
93	A surface-micromachined resonant-beam pressure-sensing structure. Journal of Microelectromechanical Systems, 2001, 10, 498-502.	2.5	27
94	Uncooled infrared bolometer arrays operating in a low to medium vacuum atmosphere: performance model and tradeoffs. , 2007, , .		27
95	Power Handling Analysis of High-Power W-Band All-Silicon MEMS Phase Shifters. IEEE Transactions on Electron Devices, 2011, 58, 1548-1555.	3.0	27
96	Silicon tube structures for a fluid-density sensor. Sensors and Actuators A: Physical, 1996, 54, 558-562.	4.1	26
97	Wafer-Scale Manufacturing of Bulk Shape-Memory-Alloy Microactuators Based on Adhesive Bonding of Titaniumâ€"Nickel Sheets to Structured Silicon Wafers. Journal of Microelectromechanical Systems, 2009, 18, 1309-1317.	2.5	26
98	Static Zero-Power-Consumption Coplanar Waveguide Embedded DC-to-RF Metal-Contact MEMS Switches in Two-Port and Three-Port Configuration. IEEE Transactions on Electron Devices, 2010, 57, 1659-1669.	3.0	26
99	A balanced dual-diaphragm resonant pressure sensor in silicon. IEEE Transactions on Electron Devices, 1990, 37, 648-653.	3.0	25
100	A balanced resonant pressure sensor. Sensors and Actuators A: Physical, 1990, 21, 336-341.	4.1	24
101	Characteristics of a hot-wire microsensor for time-dependent wall shear stress measurements. Experiments in Fluids, 2003, 35, 240-251.	2.4	24
102	Single nucleotide polymorphism analysis by allele-specific primer extension with real-time bioluminescence detection in a microfluidic device. Journal of Chromatography A, 2003, 1014, 37-45.	3.7	24
103	Small piezoresistive silicon microphones specially designed for the characterization of turbulent gas flows. Sensors and Actuators A: Physical, 1995, 46, 151-155.	4.1	23
104	Pyrosequencing in a Microfluidic Flow-Through Device. Analytical Chemistry, 2005, 77, 7505-7511.	6.5	22
105	A Low-Temperature Thermopneumatic Actuation Principle for Gas Bubble Microvalves. Journal of Microelectromechanical Systems, 2007, 16, 765-774.	2.5	22
106	Low-cost far infrared bolometer camera for automotive use. , 2007, , .		22
107	A free-hanging strain-gauge for ultraminiaturized pressure sensors. Sensors and Actuators A: Physical, 2002, 97-98, 75-82.	4.1	21
108	Characterization of transfer-bonded silicon bolometer arrays. , 2004, , .		21

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109	SMA Microvalves for Very Large Gas Flow Control Manufactured Using Wafer-Level Eutectic Bonding. IEEE Transactions on Industrial Electronics, 2012, 59, 4895-4906.	7.9	21
110	Through-Glass Vias for Glass Interposers and MEMS Packaging Applications Fabricated Using Magnetic Assembly of Microscale Metal Wires. IEEE Access, 2018, 6, 44306-44317.	4.2	21
111	Scalable Manufacturing of Single Nanowire Devices Using Crack-Defined Shadow Mask Lithography. ACS Applied Materials & Interfaces, 2019, 11, 8217-8226.	8.0	21
112	An Autonomous Microfluidic Device for Generating Volume-Defined Dried Plasma Spots. Analytical Chemistry, 2019, 91, 7125-7130.	6.5	21
113	New fluid filter structure in silicon fabricated using a selfâ€aligning technique. Applied Physics Letters, 1988, 53, 1566-1568.	3.3	20
114	Vibration modes of a resonant silicon tube density sensor. Journal of Microelectromechanical Systems, 1996, 5, 39-44.	2.5	20
115	Room-Temperature Sealing of Microcavities by Cold Metal Welding. Journal of Microelectromechanical Systems, 2009, 18, 1318-1325.	2.5	20
116	Wafer-Level Vacuum Sealing by Transfer Bonding of Silicon Caps for Small Footprint and Ultra-Thin MEMS Packages. Journal of Microelectromechanical Systems, 2019, 28, 460-471.	2.5	20
117	A sensor based on silicon technology for turbulence measurements. Journal of Physics E: Scientific Instruments, 1989, 22, 391-393.	0.7	19
118	A low-pressure encapsulated resonant fluid density sensor with feedback control electronics. Measurement Science and Technology, 2000, 11, 205-211.	2.6	19
119	A temperature compensated dual beam pressure sensor. Sensors and Actuators A: Physical, 2002, 100, 46-53.	4.1	19
120	Off-line integration of CE and MALDI-MS using a closedâ€“openâ€“closed microchannel system. Electrophoresis, 2007, 28, 2458-2465.	2.4	19
121	Small silicon based pressure transducers for measurements in turbulent boundary layers. Experiments in Fluids, 1994, 17, 24-31.	2.4	18
122	A small-size silicon microphone for measurements in turbulent gas flows. Sensors and Actuators A: Physical, 1994, 45, 103-108.	4.1	18
123	A lift-force flow sensor designed for acceleration insensitivity. Sensors and Actuators A: Physical, 1998, 68, 263-268.	4.1	18
124	Expandable microspheresâ€"surface immobilization techniques. Sensors and Actuators B: Chemical, 2002, 84, 290-295.	7.8	18
125	Very large scale heterogeneous integration (VLSHI) and wafer-level vacuum packaging for infrared bolometer focal plane arrays. Infrared Physics and Technology, 2013, 60, 251-259.	2.9	18
126	Evaluation of a Volumetric Dried Blood Spot Card Using a Gravimetric Method and a Bioanalytical Method with Capillary Blood from 44 Volunteers. Analytical Chemistry, 2019, 91, 5558-5565.	6.5	18

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127	Wafer-level hermetically sealed silicon photonic MEMS. Photonics Research, 2022, 10, A14.	7.0	18
128	A silicon sensor for measurement of liquid flow and thickness of fouling biofilms. Sensors and Actuators, 1988, 13, 203-221.	1.7	17
129	Consecutive microcontact printing â€" ligands for asymmetric catalysis in silicon channels. Sensors and Actuators B: Chemical, 2001, 79, 78-84.	7.8	17
130	An integrated QCM-based narcotics sensing microsystem. Lab on A Chip, 2008, 8, 1648.	6.0	17
131	Small footprint wafer-level vacuum packaging using compressible gold sealing rings. Journal of Micromechanics and Microengineering, 2011, 21, 085011.	2.6	17
132	Stress-Minimized Packaging of Inertial Sensors by Double-Sided Bond Wire Attachment. Journal of Microelectromechanical Systems, 2015, 24, 781-789.	2.5	17
133	Electrochemically Assisted Maskless Selective Removal of Metal Layers for Three-Dimensional Micromachined SOI RF MEMS Transmission Lines and Devices. Journal of Microelectromechanical Systems, 2011, 20, 899-908.	2.5	16
134	Drift-Free Micromirror Arrays Made of Monocrystalline Silicon for Adaptive Optics Applications. Journal of Microelectromechanical Systems, 2012, 21, 959-970.	2.5	16
135	An Improved Negative Staining Technique Using A Thin Quartz Membrane as Sample Support. Biotechnic & Histochemistry, 1987, 62, 231-236.	0.4	15
136	An optical IR-source and CO/sub 2/-chamber system for CO/sub 2/ measurements. Journal of Microelectromechanical Systems, 2000, 9, 509-516.	2.5	15
137	A diode-based two-wire solution for temperature-compensated piezoresistive pressure sensors. IEEE Transactions on Electron Devices, 2003, 50, 503-509.	3.0	15
138	A compact, low-cost microliter-range liquid dispenser based on expandable microspheres. Journal of Micromechanics and Microengineering, 2006, 16, 2740-2746.	2.6	15
139	Wafer-Level Vacuum Packaging Enabled by Plastic Deformation and Low-Temperature Welding of Copper Sealing Rings With a Small Footprint. Journal of Microelectromechanical Systems, 2017, 26, 357-365.	2.5	15
140	Design and fabrication of crack-junctions. Microsystems and Nanoengineering, 2017, 3, 17042.	7.0	15
141	Genotyping by dynamic heating of monolayered beads on a microheated surface. Electrophoresis, 2004, 25, 3712-3719.	2.4	14
142	Design and Wafer-Level Fabrication of SMA Wire Microactuators on Silicon. Journal of Microelectromechanical Systems, 2010, 19, 982-991.	2.5	14
143	A seat microvalve nozzle for optimal gas-flow capacity at large-controlled pressure. Journal of Microelectromechanical Systems, 2005, 14, 200-206.	2.5	13
144	Microfluidic devices for studies of primary cilium mediated cellular response to dynamic flow conditions. Biomedical Microdevices, 2008, 10, 555-560.	2.8	13

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145	CMOS-Integrable Piston-Type Micro-Mirror Array for Adaptive Optics Made of Mono-Crystalline Silicon using 3-D Integration. , 2009, , .		13
146	High-performance quantum-well silicon-germanium bolometers using IC-compatible integration for low-cost infrared imagers. , 2009, , .		13
147	Bactericidal surfaces prepared by femtosecond laser patterning and layer-by-layer polyelectrolyte coating. Journal of Colloid and Interface Science, 2020, 575, 286-297.	9.4	13
148	Deep-Reactive-Ion-Etched Wafer-Scale-Transferred All-Silicon Dielectric-Block Millimeter-Wave MEMS Phase Shifters. Journal of Microelectromechanical Systems, 2010, 19, 120-128.	2.5	12
149	Fulfilling the pedestrian protection directive using a long-wavelength infrared camera designed to meet both performance and cost targets. , 2006, 6198, 74.		11
150	Coplanar-waveguide embedded mechanically-bistable DC-to-RF MEMS switches. , 2007, , .		11
151	Flow Sensors. , 2008, , 209-272.		11
152	Row/Column Addressing Scheme for Large Electrostatic Actuator MEMS Switch Arrays and Optimization of the Operational Reliability by Statistical Analysis. Journal of Microelectromechanical Systems, 2008, 17, 1104-1113.	2.5	11
153	"Burst" technology with feedback-loop control for capacitive detection and electrostatic excitation of resonant silicon sensors. IEEE Transactions on Electron Devices, 2000, 47, 2228-2235.	3.0	10
154	Thermosetting nano-imprint resists: novel materials for adhesive wafer bonding. , 2007, , .		10
155	Wafer-Level Process for Single-Use Buckling-Film Microliter-Range Pumps. Journal of Microelectromechanical Systems, 2007, 16, 795-801.	2.5	10
156	Liquid Aspiration and Dispensing Based on an Expanding PDMS Composite. Journal of Microelectromechanical Systems, 2008, 17, 1254-1262.	2.5	10
157	Robust actuation of silicon MEMS using SMA wires integrated at wafer-level by nickel electroplating. Sensors and Actuators A: Physical, 2013, 189, 108-116.	4.1	10
158	Dynamic simulation model for a vibrating fluid density sensor. Sensors and Actuators A: Physical, 1999, 76, 213-224.	4.1	9
159	A low-pressure encapsulated deep reactive ion etched resonant pressure sensor electrically excited and detected using `burst' technology. Journal of Micromechanics and Microengineering, 2000, 10, 209-217.	2.6	9
160	Hybrid-mounted micromachined aluminum hotwires for wall shear-stress measurements. Journal of Microelectromechanical Systems, 2005, 14, 254-260.	2.5	9
161	A wafer-level liquid cavity integrated amperometric gas sensor with ppb-level nitric oxide gas sensitivity. Journal of Micromechanics and Microengineering, 2015, 25, 105013.	2.6	9
162	Gas diffusion and evaporation control using EWOD actuation of ionic liquid microdroplets for gas sensing applications. Sensors and Actuators B: Chemical, 2018, 267, 647-654.	7.8	9

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163	A microfluidic device for TEM sample preparation. Lab on A Chip, 2020, 20, 4186-4193.	6.0	9
164	A capacitively excited and detected resonant pressure sensor with temperature compensation. Sensors and Actuators A: Physical, 1992, 32, 639-647.	4.1	8
165	A low-power high-flow shape memory alloy wire gas microvalve. Journal of Micromechanics and Microengineering, 2012, 22, 075002.	2.6	8
166	Hermetic integration of liquids using high-speed stud bump bonding for cavity sealing at the wafer level. Journal of Micromechanics and Microengineering, 2012, 22, 045021.	2.6	8
167	MEMS reconfigurable millimeter-wave surface for V-band rectangular-waveguide switch. International Journal of Microwave and Wireless Technologies, 2013, 5, 341-349.	1.9	8
168	A low-power MEMS tunable photonic ring resonator for reconfigurable optical networks. , 2015, , .		8
169	Media protected surface micromachined leverage beam pressure sensor. Journal of Micromechanics and Microengineering, 2001, 11, 617-622.	2.6	7
170	Out-of-Plane Knife-Gate Microvalves for Controlling Large Gas Flows. Journal of Microelectromechanical Systems, 2006, 15, 1281-1288.	2.5	7
171	Localized removal of the Auâ€“Si eutectic bonding layer for the selective release of microstructures. Journal of Micromechanics and Microengineering, 2009, 19, 105014.	2.6	7
172	Toward 17Ã‚Âµm pitch heterogeneously integrated Si/SiGe quantum well bolometer focal plane arrays. Proceedings of SPIE, 2011, , .	0.8	7
173	Batch Transfer of Radially Expanded Die Arrays for Heterogeneous Integration Using Different Wafer Sizes. Journal of Microelectromechanical Systems, 2012, 21, 1077-1083.	2.5	7
174	A MEMS-based passive hydrocephalus shunt for body position controlled intracranial pressure regulation. Biomedical Microdevices, 2014, 16, 529-536.	2.8	7
175	A silicon transducer for the determination of wall-pressure fluctuations in turbulent boundary layers. Flow, Turbulence and Combustion, 1993, 51, 203-207.	0.2	6
176	Time-Efficient Quasi-Static Algorithm for Simulation of Complex Single-Sided Clamped Electrostatic Actuators. Journal of Microelectromechanical Systems, 2007, 16, 373-382.	2.5	6
177	Tapered Deep Reactive Ion Etching: Method and Characterization. , 2007, , .		6
178	Fluid dynamic behavior of dispensing small droplets through a thin liquid film. Microfluidics and Nanofluidics, 2010, 9, 303-311.	2.2	6
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